#### General Description

The MAX509/MAX510 are quad, serial-input, 8-bit voltage-output digital-to-analog converters (DACs). They operate with a single +5V supply or dual ±5V supplies. Internal, precision buffers swing rail-to-rail. The reference input range includes both supply rails.

The MAX509 has four separate reference inputs, allowing each DAC's full-scale range to be set independently. 20-pin DIP, SSOP, and SO packages are available. The MAX510 is identical to the MAX509 except it has two reference inputs, each shared by two DACs. The MAX510 is housed in space-saving 16-pin DIP and SO packages.

The serial interface is double-buffered: A 12-bit input shift register is followed by four 8-bit buffer registers and four 8-bit DAC registers. A 12-bit serial word is used to load data into each register. Both input and DAC registers can be updated independently or simultaneously with single software commands. Two additional asynchronous control pins provide simultaneous updating (LDAC) or clearing (CLR) of input and DAC registers.

The interface is compatible with Microwire<sup>TM</sup> and SPI/ QSPI<sup>TM</sup>. All digital inputs and outputs are TTL/CMOS compatible. A buffered data output provides for readback or daisy-chaining of serial devices.

#### CLR DOUT LDAC AGND DGND VSS VDD REFB RFFA MAXIM DECODE CONTROL | | | 🕇 111 OLITA INPU1 DAC DAC A REG A REG A DUTE 12-BIT INPUT DAC DAC B SHIFT REG E REG B REGISTER UT( INPU1 DA( DAC C REG C REG UTC SR INPUT DAC DAC D REG D ONTRO REG D CS DIN SCLK REFC REFD Functional Diagrams continued at end of data sheet.

### Functional Diagrams

#### \_\_Features

- Single +5V or Dual ±5V Supply Operation
- Output Buffer Amplifiers Swing Rail-to-Rail
- Reference Input Range Includes Both Supply Rails
- Calibrated Offset, Gain, and Linearity (1LSB TUE)
- 10MHz Serial Interface, Compatible with SPI, QSPI (CPOL = CPHA = 0) and Microwire
- Double-Buffered Registers for Synchronous Updating
- Serial Data Output for Daisy-Chaining
- Power-On Reset Clears Serial Interface and Sets All Registers to Zero

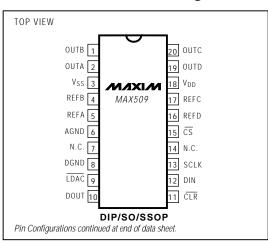
#### \_Ordering Information

TEMP. RANGE	PIN-PACKAGE	TUE (LSB)
0°C to +70°C	20 Plastic DIP	±1
0°C to +70°C	20 Plastic DIP	±1 1/2
0°C to +70°C	20 Wide SO	±1
0°C to +70°C	20 Wide SO	±1 1/2
0°C to +70°C	20 SSOP	±1
0°C to +70°C	20 SSOP	±1 1/2
0°C to +70°C	Dice*	±1 1/2
	0°C to +70°C 0°C to +70°C 0°C to +70°C 0°C to +70°C 0°C to +70°C 0°C to +70°C 0°C to +70°C	0°C to +70°C         20 Plastic DIP           0°C to +70°C         20 Plastic DIP           0°C to +70°C         20 Wide SO           0°C to +70°C         20 Wide SO           0°C to +70°C         20 Wide SO           0°C to +70°C         20 SOP           0°C to +70°C         20 SSOP

Ordering Information continued on last page.

\* Dice are specified at +25°C, DC parameters only. \*\*Contact factory for availability and processing to MIL-STD-883.

#### Pin Configurations



Microwire is a trademark of National Semiconductor. SPI and QSPI are trademarks of Motorola.

#### M/X/M

\_ Maxim Integrated Products 1

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### ABSOLUTE MAXIMUM RATINGS

V <sub>DD</sub> to DGND	0.3V, +6V
V <sub>DD</sub> to AGND	0.3V, +6V
Vss to DGND	6V, +0.3V
Vss to AGND	6V, +0.3V
V <sub>DD</sub> to V <sub>SS</sub> 0	.3V, +12V
Digital Input Voltage to DGND0.3V, (VE	)D + 0.3V)
REF(V <sub>SS</sub> - 0.3V), (V <sub>E</sub>	)D + 0.3V)
OUT	.VDD, VSS
Maximum Current into Any Pin	50mA
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )	
16-Pin Plastic DIP (derate 10.53mW/°C above +70°C)	842mW
16-Pin Wide SO (derate 9.52mW/°C above +70°C)	762mW
16-Pin CERDIP (derate 10.00mW/°C above +70°C)	800mW
Note: The outputs may be shorted to VDD, VSS, or AG	ND if the pa

20-Pin Plastic DIP (derate 11.11mW/°C above +70°C)....889mW 20-Pin Wide SO (derate 10.00mW/°C above +70°C)......800mW 20-Pin SSOP (derate 10.00mW/°C above +70°C).......800mW 20-Pin CERDIP (derate 11.11mW/°C above +70°C).......889mW Operating Temperature Ranges:

MAX5C	0°C to +70°C
MAX5E	40°C to +85°C
MAX5MJ	55°C to +125°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10sec)	+300°C

Iote: The outputs may be shorted to V<sub>DD</sub>, V<sub>SS</sub>, or AGND if the package power dissipation is not exceeded. Typical short-circuit current to AGND is 50mA. Do not bias AGND more than +1V above DGND, or more than 2.5V below DGND.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

(V<sub>DD</sub> = +5V ±10%, V<sub>SS</sub> = 0V to -5.5V, V<sub>REF</sub> = 4V, AGND = DGND = 0V, R<sub>L</sub> = 10k $\Omega$ , C<sub>L</sub> = 100pF, T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITION	S	MIN	TYP	MAX	UNITS	
STATIC ACCURACY								
Resolution				8			Bits	
		VREF = +4V,	MAX5A			±1		
Total Upadiusted Error	TUF	$V_{SS} = 0V \text{ or } -5V \pm 10\%$	MAX5B			±1.5	I SB	
Total Unadjusted Error	IUE	VREF = -4V,	MAX5A			±1	LSB	
		$V_{SS} = -5V \pm 10\%$	MAX5B			±1.5		
Differential Nonlinearity	Nonlinearity DNL Guaranteed monotonic					±1	LSB	
			MAX5C			14		
		Code = 00 hex, $V_{SS} = 0V$	MAX5E			16	- mV	
Zana Cada Fara	705	155 01	MAX5M			20		
Zero-Code Error	ZCE	Code = 00 hex, V <sub>SS</sub> = -5V ±10%	MAX5C			±14		
			MAX5E			±16		
			MAX5M			±20		
Zero-Code-Error Supply Rejection		$\begin{array}{l} Code = 00 \ hex, \ V_{DD} = 5V \\ V_{SS} = 0V \ or \ -5V \ \pm 10\% \end{array}$	′ ±10%,		1	2	mV	
Zero-Code Temperature Coefficient		Code = 00 hex			±10		µV/°C	
Full-Scale Error		Code = FF hex				±14	mV	
		Code = FF hex.	MAX5C		1	4		
Full-Scale-Error Supply Rejection		$V_{DD} = +5V \pm 10\%$ ,	MAX5E		1	8	mV	
		$V_{SS} = 0V \text{ or } -5V \pm 10\%$	MAX5M		1	12	1	
Full-Scale-Error Temperature Coefficient		Code = FF hex			±10		µV/°C	

### **ELECTRICAL CHARACTERISTICS (continued)**

(V<sub>DD</sub> = +5V ±10%, V<sub>SS</sub> = 0V to -5.5V, V<sub>REF</sub> = 4V, AGND = DGND = 0V, R<sub>L</sub> = 10k $\Omega$ , C<sub>L</sub> = 100pF, T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITION	S	MIN	TYP	MAX	UNITS
REFERENCE INPUTS		1		1			
Input Voltage Range				VSS		VDD	V
			MAX509	16	24		
Input Resistance (Note 1)		Code = 55 hex	MAX510	8	12		kΩ
			MAX509		15		
Input Capacitance (Note 2)		Code = 00 hex	MAX510		30		pF
Channel-to-Channel Isolation		(Note 3)			-60		dB
AC Feedthrough		(Note 4)			-70		dB
DAC OUTPUTS							
Full-Scale Output Voltage				Vss		Vdd	V
		VREF = 4V, load regulatio	n ≤ 1/4LSB	2			
		VREF = -4V, V <sub>SS</sub> = -5V $\pm 1$ load regulation $\leq 1/4$ LSB	0%,	2			
Resistive Load		VREF = $V_{DD}$ MAX5C/E, load regulation $\leq$ 1LSB	,	10			kΩ
		VREF = $V_{DD}$ MAX5M, load regulation $\leq 2LSB$	10				
DIGITAL INPUTS							
Input High Voltage	VIH			2.4			V
Input Low Voltage	VIL					0.8	V
Input Current	lın	VIN = 0V or VDD				1.0	μΑ
Input Capacitance	CIN	(Note 5)				10	рF
DIGITAL OUTPUTS				1			
Output High Voltage	Voh	ISOURCE = 0.2mA		V <sub>DD</sub> - 0.5			V
Output Low Voltage	Vol	I <sub>SINK</sub> = 1.6mA				0.4	V
DYNAMIC PERFORMANCE							
			MAX5C	1.0			
Voltage-Output Slew Rate		Positive and negative	MAX5E	0.7			V/µs
			MAX5M	0.5			1
Output Settling Time (Note 6)		To 1/2LSB, 10kΩ II 100pF	load		6		μs
Digital Feedthrough		Code = 00 hex, all digital from 0V to V <sub>DD</sub>	inputs		5		nV-s
Digital-to-Analog Glitch Impulse		Code 128→127			12		nV-s
Signal-to-Noise + Distortion Ratio	SINAD	VREF = 4V <sub>p-p</sub> at 1kHz, V <sub>D</sub> code = FF hex		87		dB	
		VREF = 4V <sub>p-p</sub> at 20kHz, V	$SS = -5V \pm 10\%$		74		1
Multiplying Bandwidth		VREF = 0.5Vp-p, 3dB ban	dwidth		1		MHz
Wideband Amplifier Noise					60		μV <sub>RM</sub>

M/IXI/M

### **ELECTRICAL CHARACTERISTICS (continued)**

(V<sub>DD</sub> = +5V ±10%, V<sub>SS</sub> = 0V to -5.5V, V<sub>REF</sub> = 4V, AGND = DGND = 0V, R<sub>L</sub> = 10k $\Omega$ , C<sub>L</sub> = 100pF, T<sub>A</sub> = T<sub>MIN</sub> to T<sub>MAX</sub>, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNITS	
POWER SUPPLIES							
Positive Supply Voltage	VDD	For specified performanc	For specified performance			5.5	V
Negative Supply Voltage	VSS	For specified performance		-5.5		0	V
Positive Supply Current	ממו	Outputs unloaded, all	MAX5C/E		5	10	mA
Positive Supply Current	UU	digital inputs = 0V or V <sub>DD</sub>	MAX5M		5	12	
Negative Supply Current	Iss	$V_{SS} = -5V \pm 10\%$ , outputs unloaded, all digital	MAX5C/E		5	10	mA
Negative Supply Current	155	inputs = 0V or V <sub>DD</sub>	MAX5M		5	12	

Note 1: Input resistance is code dependent. The lowest input resistance occurs at code = 55 hex.

Note 2: Input capacitance is code dependent. The highest input capacitance occurs at code = 00 hex.
 Note 3: VREF = 4V<sub>p-p</sub>, 10kHz. Channel-to-channel isolation is measured by setting the code of one DAC to FF hex and setting the code of all other DACs to 00 hex.

- $\label{eq:VREF} \begin{array}{l} \text{Note 4: } V\text{REF} = 4V_{\text{p-p}}, 10\text{ kHz}. \ \text{DAC code} = 00 \ \text{hex}. \\ \text{Note 5: } Guaranteed \ \text{by design}. \\ \text{Note 6: } Output \ \text{settling time is measured } \text{by taking the code from 00 hex to FF hex, and from FF hex to 00 hex}. \end{array}$

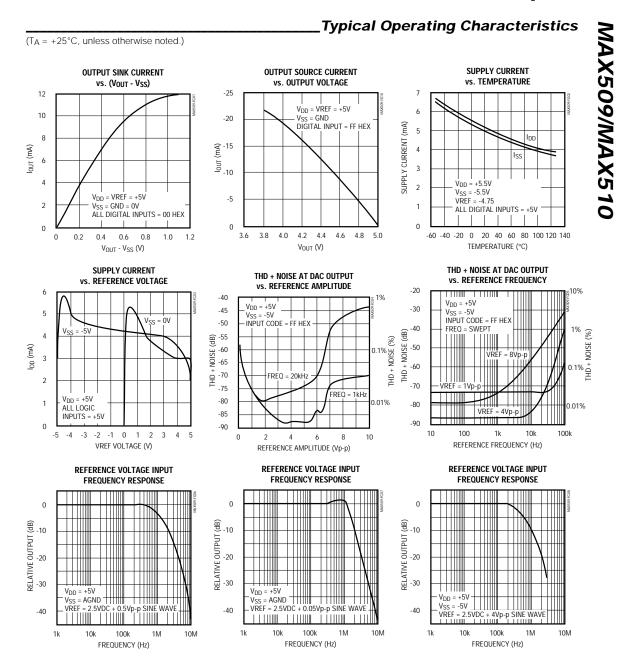
### TIMING CHARACTERISTICS

 $(V_{DD} = +5V \pm 10\%, V_{SS} = 0V$  to -5V,  $V_{REF} = 4V$ , AGND = DGND = 0V,  $C_L = 50pF$ ,  $T_A = T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
I DAC Pulse Width Low	<b>4</b>	MAX5C/E	40	20		
LDAC Pulse widin Low	tldw.	MAX5M	50	25		ns
CS Rise to LDAC Fall Setup Time	tcll	(Notes 7, 8)	0			ns
CLR Pulse Width Low	tcı w	MAX5C/E	40	20		ns
CER Puise Width Low	ICLW	MAX5M	50	25		115
SERIAL INTERFACE TIMING						
CS Fall to SCLK Setup Time	tess	MAX5C/E	40			ns
CS Fail to SCER Setup Time	iCSS	MAX5M	50			113
SCLK Fall to $\overline{CS}$ Rise Hold Time	tCSH2		0			ns
SCLK Rise to $\overline{\text{CS}}$ Rise Hold Time	tCSH1	(Note 9)	40			ns
SCLK Fall to $\overline{CS}$ Fall Hold Time	tCSH0	(Note 7)	0			ns
DIN to SCLK Rise Setup Time	tps	MAX5C/E	40			ns
Divito SCER Rise Setup Time	UDS .	MAX5M	50			113
DIN to SCLK Rise Hold Time	tDH		0			ns
SCLK Clock Frequency	fci k	MAX5C/E		20	12.5	MHz
SCER Clock frequency	ICLK	MAX5M		20	10	IVITIZ
SCLK Pulse Width High	tсн	MAX5C/E	40			ns
SCER Fulse Width High	чСН	MAX5M	50			115
SCLK Pulse Width Low	tci	MAX5C/E	40			ns
SCEN FUISE WIUITI EOW	ICL	MAX5M	50			115
SCLK to DOUT Valid	tpo	MAX5C/E	10		100	ns
	LDO	MAX5M	10		100	113

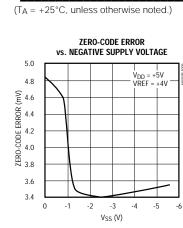
Note 7: Guaranteed by design.
 Note 8: If LDAC is activated prior to CS's rising edge, it must stay low for t<sub>LDW</sub> or longer after CS goes high.
 Note 9: Minimum delay from 12th clock cycle to CS rise.

M/IXI/N

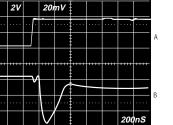


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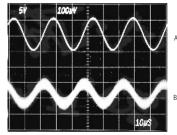




WORST-CASE 1LSB DIGITAL STEP CHANGE



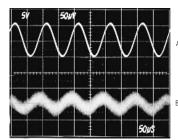
A = CS, 2V/div B = OUTA, 20mV ~ TIMEBASE = 200ns/div **REFERENCE FEEDTHROUGH AT 40kHz** 



 $\begin{array}{l} A=\text{REFA},\,10V_{p\cdot p}\\ B=\text{OUTA},\,100\mu V/div,\,UNLOADED\\ TIMEBASE=10\mu s/div\\ V_{DD}=+5V,\,V_{SS}=-5V\\ CODE=ALL\ 0s \end{array}$ 

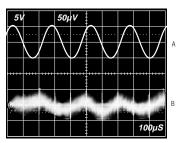
**Typical Operating Characteristics (continued)** 

#### **REFERENCE FEEDTHROUGH AT 10kHz**



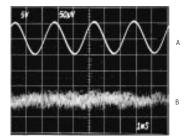
 $\label{eq:approx} \begin{array}{l} \mathsf{A} = \mathsf{REFA}, \ \mathsf{10V}_{p\text{-}p} \\ \mathsf{B} = \mathsf{OUTA}, \ \mathsf{50}\mu\mathsf{V}/\mathsf{div}, \ \mathsf{UNLOADED} \\ \mathsf{TIMEBASE} = \mathsf{50}\mu\mathsf{s}/\mathsf{div} \end{array}$ 

**REFERENCE FEEDTHROUGH AT 4kHz** 



 $\label{eq:approx} \begin{array}{l} \mathsf{A} = \mathsf{REFA}, \ \mathsf{10V}_{p\text{-}p} \\ \mathsf{B} = \mathsf{OUTA}, \ \mathsf{50}\mu\mathsf{V}/\mathsf{div}, \ \mathsf{UNLOADED} \\ \mathsf{TIMEBASE} = \mathsf{100}\mu\mathsf{s}/\mathsf{div} \end{array}$ 

**REFERENCE FEEDTHROUGH AT 400Hz** 

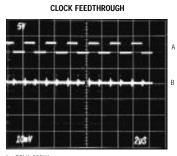


 $\label{eq:alpha} \begin{array}{l} \mathsf{A} = \mathsf{REFA}, \ \mathsf{10V}_{p\text{-}p} \\ \mathsf{B} = \mathsf{OUTA}, \ \mathsf{50}\mu\mathsf{V}/\mathsf{div}, \ \mathsf{UNLOADED} \\ \mathsf{TIMEBASE} = \mathsf{1ms}/\mathsf{div} \end{array}$ 

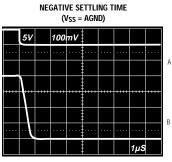
M/XI/M

### \_Typical Operating Characteristics (continued)

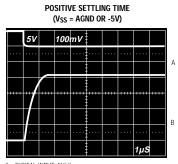
 $(T_A = +25^{\circ}C, unless otherwise noted.)$ 



A = SCLK, 333kHz B = OUT\_, 10mV/div TIMEBASE = 2µs/div



 $\label{eq:approx_state} \begin{array}{l} A = DIGITAL INPUT, 5V/div \\ B = OUT_, 2V/div \\ TIMEBASE = 1 \mu s/div \\ V_{DD} = +5V \\ REF_ = +4V \\ ALL BITS ON TO ALL BITS OFF \\ R_L = 10k \boldsymbol{\Omega}, \ C_L = 100 pF \end{array}$ 



 $\label{eq:approx_state} \begin{array}{l} A = DIGITAL INPUT, 5V/div \\ B = OUT_, 2V/div \\ TIMEBASE = 1 \mu s/div \\ V_{DD} = +5V \\ REF_ = +4V \\ ALL BITS OFF TO ALL BITS ON \\ R_L = 10k \Omega, \ C_L = 100 pF \end{array}$ 

 SV
 100 mV
 Image: Constraint of the second s

 $\label{eq:approx_appr$ 

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MAX509/MAX510

Р	IN		
MAX509	MAX510	NAME	FUNCTION
1	1	OUTB	DAC B Voltage Output
2	2	OUTA	DAC A Voltage Output
3	3	Vss	Negative Power Supply, 0V to -5V ±10%. Connect to AGND for single-supply operation
4	-	REFB	Reference Voltage Input for DAC B
-	4	REFAB	Reference Voltage Input for DACs A and B
5	-	REFA	Reference Voltage Input for DAC A
6	5	AGND	Analog Ground
7, 14	-	N.C.	Not Internally Connected
8	6	DGND	Digital Ground
9	7	LDAC	Load DAC Input (active low). Driving this asynchronous input low (level sensitive) transfers the contents of each input latch to its respective DAC latch.
10	8	DOUT	Serial Data Output. Can sink and source current. Data at DOUT is adjustable to be clocked out on rising or falling edge of SCLK.
11	9	CLR	Clear DAC input (active low). Driving CLR low causes an asynchronous clear of input and DAC registers and sets all DAC outputs to zero.
12	10	DIN	Serial Data Input. TTL/CMOS-compatible input. Data is clocked into DIN on the rising edge of SCLK. CS must be low for data to be clocked in.
13	11	SCLK	Serial Clock Input. Data is clocked in on the rising edge and clocked out on either the rising (default) or the falling edge.
15	12	CS	Chip-Select Input (active low). Data is shifted in and out when $\overline{\text{CS}}$ is low. Programming commands are executed when $\overline{\text{CS}}$ rises.
16	-	REFD	Reference Voltage Input for DAC D
-	13	REFCD	Reference Voltage Input for DACs C and D
17	_	REFC	Reference Voltage Input for DAC C
18	14	VDD	Positive Power Supply, +5V ±10%
19	15	OUTD	DAC D Output Voltage
20	16	OUTC	DAC C Output Voltage

**Pin Description** 

#### Detailed Description

#### Serial Interface

At power-on, the serial interface and all DACs are cleared and set to code zero. The serial data output (DOUT) is set to transition on SCLK's rising edge.

The MAX509/MAX510 communicate with microprocessors through a synchronous, full-duplex, 3-wire interface (Figure 1). Data is sent MSB first and can be transmitted in one 4-bit and one 8-bit (byte) packet or in one 12-bit word. If a 16-bit control word is used, the first four bits are ignored. A 4-wire interface adds a line for LDAC and allows asynchronous updating. The serial clock (SCLK) synchronizes the data transfer. Data is transmitted and received simultaneously.

Figure 2 shows a detailed serial interface timing. Please note that the clock should be low if it is stopped

between updates. DOUT does not go into a high-impedance state if the clock or  $\overline{\text{CS}}$  is high.

Serial data is clocked into the data registers in MSBfirst format, with the address and configuration information preceding the actual DAC data. Data is clocked in on SCLK's rising edge while CS is low. Data at DOUT is clocked out 12 clock cycles later, either at SCLK's rising edge (default or mode 1) or falling edge (mode 0).

Chip select  $\overline{(CS)}$  must be low to enable the DAC. If  $\overline{CS}$  is high, the interface is disabled and DOUT remains unchanged.  $\overline{CS}$  must go low at least 40ns before the first rising edge of the clock pulse to properly clock in the first bit. With  $\overline{CS}$  low, data is clocked into the MAX509/MAX510's internal shift register on the rising edge of the external serial clock. SCLK can be driven at rates up to 12.5MHz.

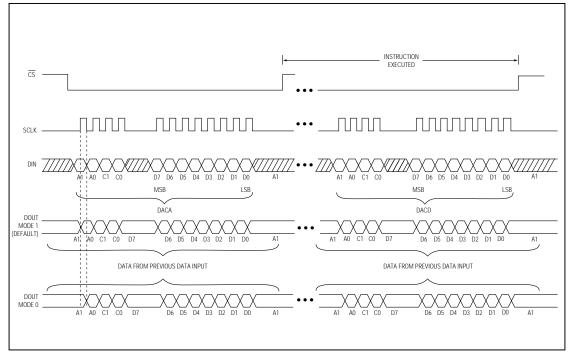


Figure 1. MAX509/MAX510 3-Wire Interface Timing

**MIXIM** 

MAX509/MAX510



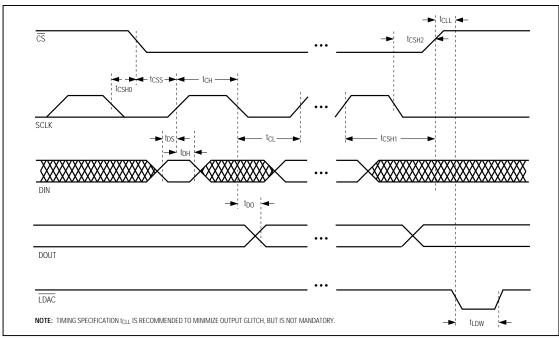


Figure 2. Detailed Serial Interface Timing (Mode 0 Shown)

		12-Bit Se	rial Word		LDAC	Function
A1	A0	C1	C0	D7 D0	LDAC	Function
0	0	0	1	8-Bit DAC Data	1	Load DAC A input register, DAC output unchanged.
0	1	0	1	8-Bit DAC Data	1	Load DAC B input register, DAC output unchanged.
1	0	0	1	8-Bit DAC Data	1	Load DAC C input register, DAC output unchanged.
1	1	0	1	8-Bit DAC Data	1	Load DAC D input register, DAC output unchanged.
0	0	1	1	8-Bit DAC Data	1	Load input and DAC register A.
0	1	1	1	8-Bit DAC Data	1	Load input and DAC register B.
1	0	1	1	8-Bit DAC Data	1	Load input and DAC register C.
1	1	1	1	8-Bit DAC Data	1	Load input and DAC register D.
Х	0	0	0	8-Bit DAC Data	Х	Update all DACs from shift register.
Х	1	0	0	X X X X X X X X X	Х	No Operation (NOP), shifts data in shift register.
0	х	1	0	****	Х	"LDAC" Command, all DACs updated from respective input registers.
1	1	1	0	*****	Х	Mode 1, DOUT clocked out on rising edge of SCLK (default). All DACs updated from respective input registers.
1	0	1	0	****	х	Mode 0, DOUT clocked out on falling edge of SCLK. All DACs updated from input registers.

### Table 1. Serial-Interface Programming Commands

**WIXIW** 

#### Serial Input Data Format and Control Codes

The 12-bit serial input format shown in Figure 3 comprises two DAC address bits (A1, A0), two control bits (C1, C0) and eight bits of data (D0...D7).

The 4-bit address/control code configures the DAC as shown in Table 1.

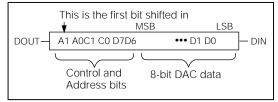


Figure 3. Serial Input Format

#### Load Input Register, DAC Registers Unchanged (Single Update Operation)

A1	A0	C1	C0	D7	D6	D5	D4	D3	D2	D1	D0
Add	ress	0	1	8-Bit Data							
$(\overline{I}\overline{DAC} = H)$											

When performing a single update operation, A1 and A0 select the respective input register. At the rising edge of  $\overline{CS}$ , the selected input register is loaded with the current shift-register data. All DAC outputs remain unchanged. This preloads individual data in the input register without changing the DAC outputs.

Load	Input	and	DAC	Registers
------	-------	-----	-----	-----------

A1	A0	C1	C0	D7	D6	D5	D4	D3	D2	D1	D0
Add	ress	1	1				8-Bit	Data			

 $(\overline{LDAC} = H)$ 

This command directly loads the selected DAC register at  $\overline{CS}$ 's rising edge. A1 and A0 set the DAC address. Current shift-register data is placed in the selected input and DAC registers.

For example, to load all four DAC registers simultaneously with individual settings (DAC A = 1V, DAC B = 2V, DAC C = 3V and DAC D = 4V), five commands are required. First, perform four single input register update operations. Next, perform an "LDAC" command as a fifth command. All DACs will be updated from their respective input registers at the rising edge of  $\overline{CS}$ .

#### Update All DACs from Shift Registers

A1	A0	C1	C0	D7	D6	D5	D4	D3	D2	D1	D0
Х	0	0	0	8-Bit DAC Data							

 $(\overline{LDAC} = x)$ 

All four DAC registers are updated with shift-register data. This command allows all DACs to be set to any analog value within the reference range. This command can be used to substitute CLR if code 00 hex is programmed, which clears all DACs.

#### No Operation (NOP)

A1	A0	C1	A1 A0 C1 C0 D7 D6 D5 D4 D3 D2 D1 D0									
x 1 0 0 x x x x x x x									Х	Х		
$\overline{(DAC} = x)$												

The NOP command (no operation) allows data to be shifted through the MAX509/MAX510 shift register without affecting the input or DAC registers. This is useful in daisy chaining (also see the *Daisy-Chaining Devices* section). For this command, the data bits are "Don't Cares." As an example, three MAX509/MAX510s are daisy-chained (A, B and C), and DAC A and DAC C need to be updated. The 36-bit-wide command would consist of one 12-bit word for device C, followed by an NOP instruction for device B and a third 12-bit word with data for device A. At  $\overline{CS}$ 's rising edge, only device B is not updated.

#### "LDAC" Command (Software)

A1	A0	A1 A0 C1 C0 D7 D6 D5 D4 D3 D2 D1 D0										
0 x 1 0 x x x x x x x x												
$\overline{(\text{LDAC} = x)}$												

- /

All DAC registers are updated with the contents of their respective input registers at  $\overline{CS}$ 's rising edge. With the exception of using  $\overline{CS}$  to execute, this performs the same function as the asynchronous  $\overline{LDAC}$ .

Set DOUT Phase –	SCLK Rising (	Mode 1, Default)
------------------	---------------	------------------

A1	A0	C1	C0	D7	D6	D5	D4	D3	D2	D1	D0
1	1	1	0	Х	Х	Х	х	х	Х	Х	Х

#### $(\overline{LDAC} = x)$

Mode 1 resets the serial output DOUT to transition at SCLK's rising edge. This is the MAX509/MAX510's default setting after the supply voltage has been applied.

The command also loads all DAC registers with the contents of their respective input registers, and is identical to the " $\overline{\text{LDAC}}$ " command.

#### Set DOUT Phase – SCLK Falling (Mode 0)

A1         A0         C1         C0         D7         D6         D5         D4         D3         D2         D1         D0           1         0         1         0         x         <												-
1 0 1 0 x x x x x x x x	A1	A0	C1	C0	D7	D6	D5	D4	D3	D2	D1	D0
	1	0	1	0	Х	х	Х	Х	х	х	Х	х

 $<sup>(\</sup>overline{LDAC} = x)$ 

This command resets DOUT to transition at SCLK's falling edge. Once this command is issued, the phase of DOUT is latched and will not change except on power-up or if the specific command is issued that sets the phase to rising edge.

The same command also updates all DAC registers with the contents of their respective input registers, identical to the " $\overline{\text{LDAC}}$ " command.

#### LDAC Operation (Hardware)

LDAC is typically used in 4-wire interfaces (Figure 7). LDAC allows asynchronous hardware control of the DAC outputs and is level-sensitive. With LDAC low, the DAC registers are transparent and any time an input register is updated, the DAC output immediately follows.

#### Clear DACs with CLR

Strobing the  $\overline{\text{CLR}}$  pin low causes an asynchronous clear of input and DAC registers and sets all DAC outputs to zero. Similar to the LDAC pin,  $\overline{\text{CLR}}$  can be invoked at any time, typically when the device is not selected ( $\overline{\text{CS}}$  = H). When the DAC data is all zeros, this function is equivalent to the "Update all DACs from Shift Registers" command.

#### **Digital Inputs and Outputs**

Digital inputs and outputs are compatible with both TTL and 5V CMOS logic. The power-supply current ( $I_{DD}$ ) depends on the input logic levels. Using CMOS logic to drive  $\overline{CS}$ , SCLK, DIN,  $\overline{CLR}$  and  $\overline{LDAC}$  turns off the internal level translators and minimizes supply currents.

#### Serial Data Output

DOUT is the output of the internal shift register. DOUT can be programmed to clock out data on SCLK's falling edge (mode 0) or rising edge (mode 1). In mode 0, output data lags the input data by 12.5 clock cycles, maintaining compatibility with Microwire, SPI, and QSPI. In mode 1, output data lags the input by 12 clock cycles. On power-up, DOUT defaults to mode 1 timing. DOUT never three-states; it always actively drives either high or low and remains unchanged when CS is high.

#### Interfacing to the Microprocessor

The MAX509/MAX510 are Microwire, SPI, and QSPI compatible. For SPI and QSPI, clear the CPOL and CPHA configuration bits (CPOL = CPHA = 0). The SPI/QSPI CPOL = CPHA = 1 configuration can also be used if the DOUT output is ignored.

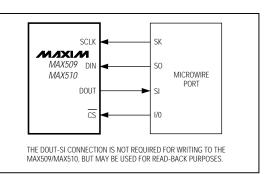


Figure 4. Connections for Microwire

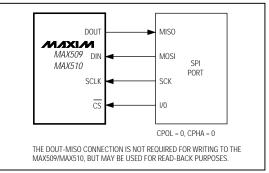


Figure 5. Connections for SPI

The MAX509/MAX510 can interface with Intel's 80C5X/80C3X family in mode 0 if the SCLK clock polarity is inverted. More universally, if a serial port is not available, three lines from one of the parallel ports can be used for bit manipulation.

Digital feedthrough at the voltage outputs is greatly minimized by operating the serial clock only to update the registers. Also see the Clock Feedthrough photo in the *Typical Operating Characteristics* section. The clock idle state is low.

#### Daisy-Chaining Devices

Any number of MAX509/MAX510s can be daisy-chained by connecting the DOUT pin of one device to the DIN pin of the following device in the chain. The NOP instruction (Table 1) allows data to be passed from DIN to DOUT without changing the input or DAC registers of the passing device. A three-wire interface updates daisy-chained or individual MAX509/MAX510s simultaneously by bringing CS high.

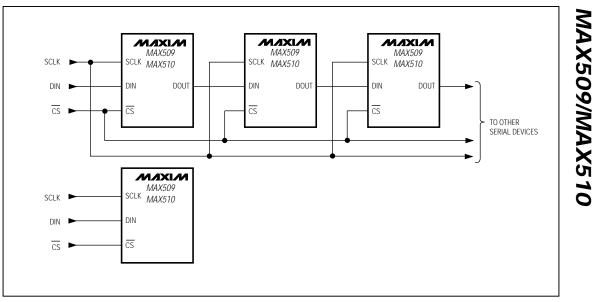


Figure 6. Daisy-chained or individual MAX509/MAX510s are simultaneously updated by bringing  $\overline{CS}$  high. Only three wires are required.

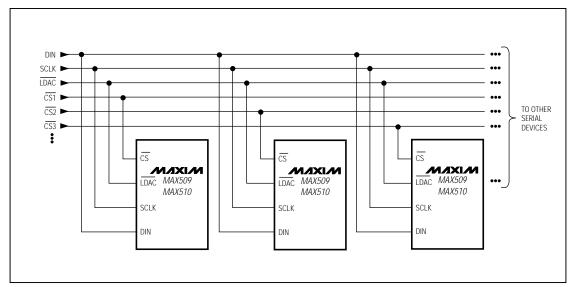


Figure 7. Multiple MAX509/MAX510 DACs sharing one DIN line. Simultaneously update by strobing  $\overline{LDAC}$ , or specifically update by enabling individual  $\overline{CS}$ .



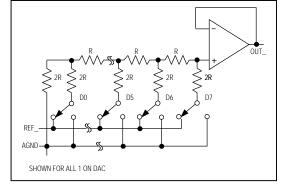


Figure 8. DAC Simplified Circuit Diagram

If multiple devices share a common DIN line, Figure 7's configuration provides simultaneous update by strobing LDAC low. CS1, CS2, CS3... are driven separately, thus controlling which data are written to devices 1, 2, 3....

### Analog Section

**DAC Operation** The MAX509/MAX510 contain four matched voltageoutput DACs. The DACs are inverted R-2R ladder networks that convert 8-bit digital words into equivalent analog output voltages in proportion to the applied reference voltages. Each DAC in the MAX509 has a separate reference input, while the two reference inputs in the MAX510 each share a pair of DACs. The two reference inputs permit different full-scale output voltage ranges for each pair of DACs. A simplified diagram of

one of the four DACs is shown in Figure 8.

#### **Reference Input**

The MAX509/MAX510 can be used for multiplying applications. The reference accepts both DC and AC signals. The voltage at each REF input sets the fullscale output voltage for its respective DAC(s). If the reference voltage is positive, both the MAX509 and MAX510 can be operated from a single supply. If dual supplies are used, the reference input can vary from VSS to VDD, but is always referred to AGND. The input impedance at REF is code dependent, with the lowest value (16k $\Omega$  for the MAX509 and 8k $\Omega$  for the MAX510) occurring when the input code is 55 hex or 0101 0101. The maximum value, practically infinity, occurs when the input code is 00 hex. Since the REF input impedance is code dependent, the DAC's reference sources must have a low output impedance (no more than  $32\Omega$ for the MAX509 and  $16\Omega$  for the MAX510) to maintain output linearity. The REF input capacitance is also code dependent: 15pF typical for the MAX509 and 30pF typical for the MAX510.

The output voltage for any DAC can be represented by a digitally programmable voltage source as:

where NB is the numerical value of the DAC's binary input code.

#### **Output Buffer Amplifiers**

All MAX509/MAX510 voltage outputs are internally buffered by precision unity-gain followers that slew at up to 1V/µs. The outputs can swing from V<sub>SS</sub> to V<sub>DD</sub>. With a 0V to +4V (or +4V to 0V) output transition, the amplifier outputs will settle to 1/2LSB in typically 6µs when loaded with 10k $\Omega$  in parallel with 100pF.

The buffer amplifiers are stable with any combination of resistive loads  $\ge 2k\Omega$  and capacitive loads  $\le 300$  pF.

#### \_Applications Information

#### Power Supply and Reference Operating Ranges

The MAX509/MAX510 are fully specified to operate with  $V_{DD} = 5V \pm 10\%$  and  $V_{SS} = 0V$  to -5.5V. 8-bit performance is guaranteed for both single- and dual-supply operation. The zero-code output error is less than 14mV when operating from a single +5V supply.

The DACs work well with reference voltages from Vss to V<sub>DD</sub>. The reference voltage is referred to AGND.

The preferred power-up sequence is to apply Vss and then V<sub>DD</sub>, but bringing up both supplies at the same time is also acceptable. In either case, the voltage applied to REF should not exceed V<sub>DD</sub> during powerup or at any other time. If proper power sequencing is not possible, connect an external Schottky diode between Vss and AGND to ensure compliance with the *Absolute Maximum Ratings*. Do not apply signals to the digital inputs before the device is fully powered up.

#### Power-Supply Bypassing and Ground Management

In single-supply operation (AGND = DGND = V<sub>SS</sub> = 0V), AGND, DGND and V<sub>SS</sub> should be connected together in a "star" ground at the chip. This ground should then return to the highest quality ground available. Bypass V<sub>DD</sub> with a 0.1 $\mu$ F capacitor, located as close to V<sub>DD</sub> and DGND as possible. In dual-supply operation, bypass V<sub>SS</sub> to AGND with 0.1 $\mu$ F.

Careful PC board layout minimizes crosstalk among DAC outputs, reference inputs, and digital inputs. Figures 9 and 10 show suggested circuit board layouts to minimize crosstalk.





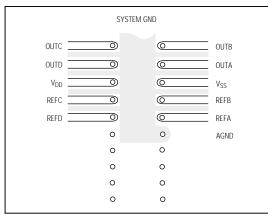


Figure 9. Suggested MAX509 PC Board Layout for Minimizing Crosstalk (Bottom View)

**Unipolar-Output, 2-Ouadrant Multiplication** In unipolar operation, the output voltages and the reference input(s) are the same polarity. Figures 11 and 12 show the MAX509/MAX510 unipolar configurations. Both devices can be operated from a single supply if the reference inputs are positive. If dual supplies are used, the reference input can vary from V<sub>SS</sub> to V<sub>DD</sub>. Table 2 shows the unipolar code.

Table 2. Unipolar Code	Table
------------------------	-------

DAC CO	NTENTS	ANALOG
MSB	LSB	OUTPUT
1111	1111	+V <sub>REF</sub> ( <u>255</u> ) 256
1000	0001	$+V_{REF}\left(\frac{129}{256}\right)$
1000	0000	$+ V_{REF} \left( \frac{128}{256} \right) = + \frac{V_{REF}}{2}$
0111	1111	$+V_{\text{REF}}\left(\frac{127}{256}\right)$
0000	0001	$+V_{\text{REF}}\left(\frac{1}{256}\right)$
0000	0000	OV

**Note:**  $1LSB = (V_{REF}) (2^{-8}) = +V_{REF} (\frac{1}{256})$ 

M/IXI/N

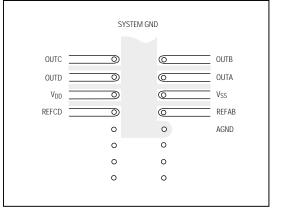


Figure 10. Suggested MAX510 PC Board Layout for Minimizing Crosstalk (Bottom View)

**Bipolar-Output, 2-Quadrant Multiplication** Bipolar-output, 2-quadrant multiplication is achieved by offsetting AGND positively or negatively. Table 3 shows the bipolar code.

AGND can be biased above DGND to provide an arbitrary nonzero output voltage for a 0 input code, as shown in Figure 13. The output voltage at OUTA is:

 $V_{OUTA} = V_{BIAS} + (NB/256)(V_{IN}),$ 

Table 3. Bipolar Code Table

DAC CO	NTENTS	ANALOG
MSB	LSB	OUTPUT
1111	1111	$+V_{REF}\left(\frac{127}{128}\right)$
1000	0001	$+V_{\text{REF}}\left(\frac{1}{128}\right)$
1000	0000	OV
0111	1111	$-V_{\text{REF}}\left(\frac{1}{128}\right)$
0000	0001	-V <sub>REF</sub> ( <u>127</u> ) 128
0000	0000	$-V_{REF}\left(\frac{128}{128}\right) = -V_{REF}$

MAX509/MAX510

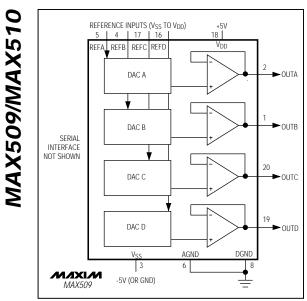
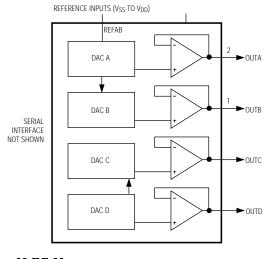


Figure 11. MAX509 Unipolar Output Circuit



MAXIM MAX510

Figure 12. MAX510 Unipolar Output Circuit

where NB represents the digital input word. Since AGND is common to all four DACs, all outputs will be offset by  $V_{BIAS}$  in the same manner. Do not bias AGND more than +1V above DGND, or more than 2.5V below DGND.

Figures 14 and 15 illustrate the generation of negative offsets with bipolar outputs. In these circuits, AGND is biased negatively (up to -2.5V with respect to DGND) to provide an arbitrary negative output voltage for a 0 input code. The output voltage at OUTA is:

OUTA = -(R2/R1)(2.5V) + (NB/256)(2.5V)(R2/R1+1)

where NB represents the digital input word. Since AGND is common to all four DACs, all outputs will be offset by V<sub>BIAS</sub> in the same manner. Table 3, with V<sub>REF</sub> = 2.5V, shows the digital code vs. output voltage for Figure 14 and 15's circuits with R1 = R2. The ICL7612 op amp is chosen because its common-mode range extends to both supply rails.

**M**/IXI/M

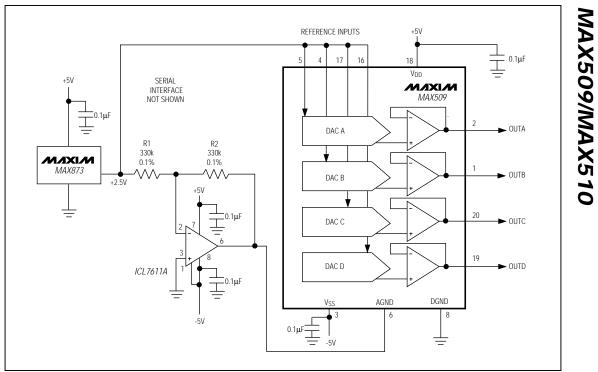


Figure 14. MAX509 AGND Bias Circuit (Negative Offset)

#### 4-Quadrant Multiplication

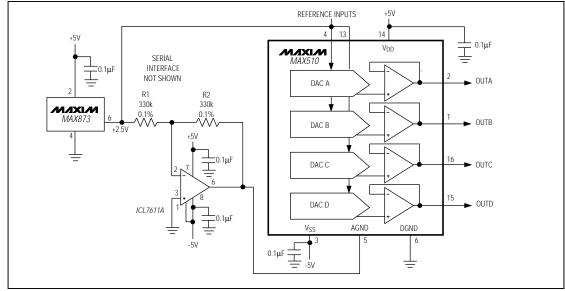
Each DAC output may be configured for 4-quadrant multiplication using Figure 16 and 17's circuit. One op amp and two resistors are required per channel. With R1 = R2:

#### $V_{OUT} = V_{REF} [2(NB/256)-1]$

where NB represents the digital word in DAC register A. The recommended value for resistors R1 and R2 is  $330k\Omega$  (±0.1%). Table 3 shows the digital code vs. output voltage for Figure 16 and 17's circuit.

M/IXI/M







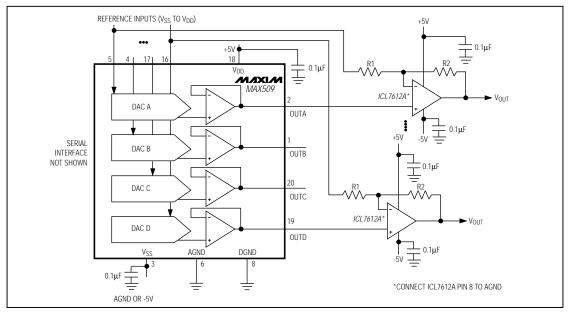


Figure 16. MAX509 Bipolar Output Circuit

M/IXI/N

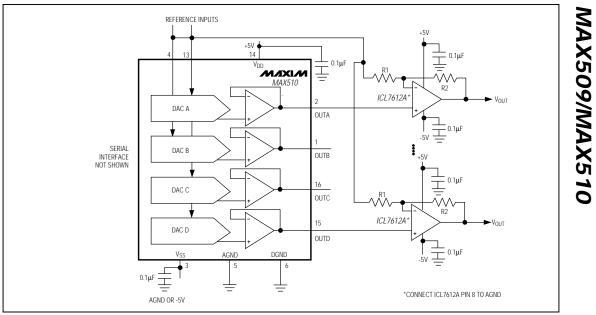
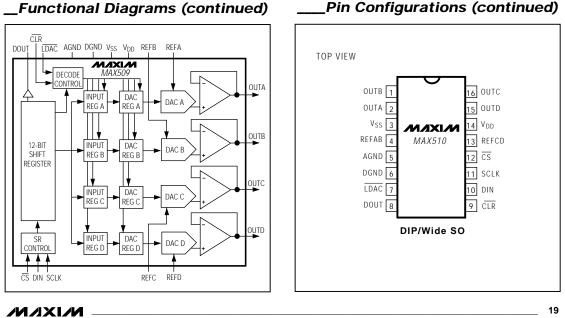


Figure 17. MAX510 Bipolar Output Circuit

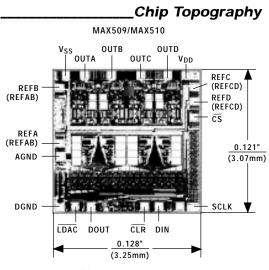


### Pin Configurations (continued)

### \_Ordering Information (continued)

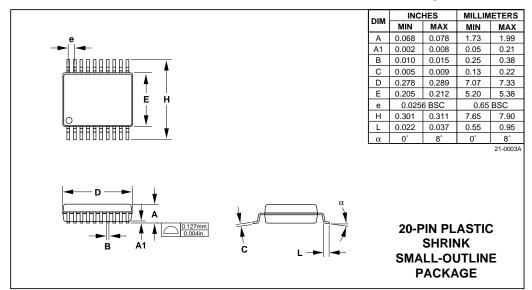
PART	TEMP. RANGE	PIN-PACKAGE	TUE (LSB)
MAX509AEPP	-40°C to +85°C	20 Plastic DIP	±1
MAX509BEPP	-40°C to +85°C	20 Plastic DIP	±1 1/2
MAX509AEWP	-40°C to +85°C	20 Wide SO	±1
MAX509BEWP	-40°C to +85°C	20 Wide SO	±1 1/2
MAX509AEAP	-40°C to +85°C	20 SSOP	±1
MAX509BEAP	-40°C to +85°C	20 SSOP	±1 1/2
MAX509AMJP	-55°C to +125°C	20 CERDIP**	±1
MAX509BMJP	-55°C to +125°C	20 CERDIP**	±1 1/
MAX510ACPE	0°C to +70°C	16 Plastic DIP	±1
MAX510BCPE	0°C to +70°C	16 Plastic DIP	±1 1/
MAX510ACWE	0°C to +70°C	16 Wide SO	±1
MAX510BCWE	0°C to +70°C	16 Wide SO	±1 1/
MAX510AEPE	-40°C to +85°C	16 Plastic DIP	±1
MAX510BEPE	-40°C to +85°C	16 Plastic DIP	±1 1/
MAX510AEWE	-40°C to +85°C	16 Wide SO	±1
MAX510BEWE	-40°C to +85°C	16 Wide SO	±1 1/
MAX510AMJE	-55°C to +125°C	16 CERDIP**	±1
MAX510BMJF	-55°C to +125°C	16 CERDIP**	±1 1/

**MAX509/MAX510** 



NOTE: LABELS IN ( ) ARE FOR MAX510 ONLY. TRANSISTOR COUNT: 2235; SUBSTRATE CONNECTED TO VDD.

#### Package Information



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